



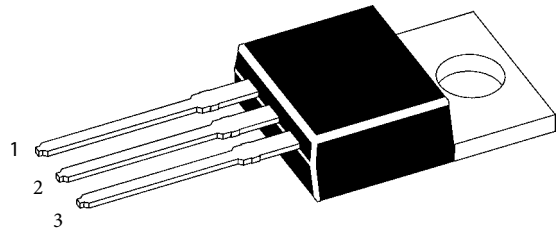
# PJM40250NTO

## Silicon N-Channel Power MOSFET

### Features

- Advanced Trench Technology
- $R_{ds(On)} < 2.5m\Omega @ V_{gs}=10v$  (Typ1.6m $\Omega$ )
- High Density Cell Design for Ultra Low  $R_{ds(On)}$
- Fully Characterized Avalanche Voltage and Current
- Excellent Package for Good Heat Dissipation

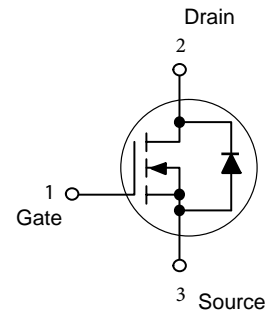
TO-220



### Applications

- Power Switching Application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply

### Schematic diagram



### Absolute Maximum Ratings

Ratings at  $T_C = 25^\circ C$  unless otherwise specified.

Parameter	Symbol	Value	Units
Drain-to-Source Voltage	$V_{DS}$	40	V
Continuous Drain Current	$I_D$	250	A
Pulsed Drain Current <sup>Note 1</sup>	$I_{DM}$	1000	A
Gate-to-Source Voltage	$V_{GS}$	$\pm 20$	V
Single Pulse Avalanche Energy	$E_{AS}$	1300	mJ
Power Dissipation	$P_D$	242	W
Operating Junction Temperature	$T_J$	175	$^\circ C$
Storage Temperature Range	$T_{STG}$	-55 to 175	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Value	Units
Thermal Resistance, Junction-to-Case <sup>Note 1</sup>	$R_{\theta JC}$	0.62	$^\circ C/W$

Note: 1. Surface Mounted on FR4 Board,  $t \leq 10sec$ .



# PJM40250NTO

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### Electrical Characteristics

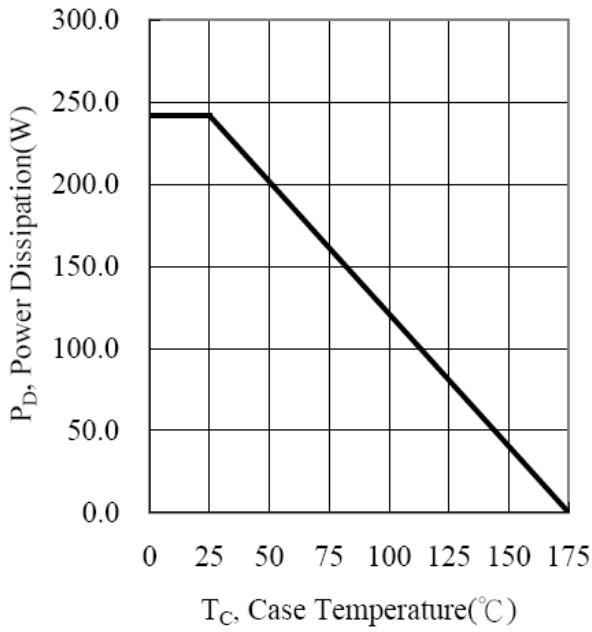
Ratings at  $T_C = 25^\circ\text{C}$  unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	40	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.0	-	3.0	V
Gate Leakage Current	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 32V, V_{GS} = 0V, T_A = 25^\circ\text{C}$	-	-	1.0	$\mu A$
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 80A$	-	1.6	2.5	m $\Omega$
<b>Dynamic Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{DD} = 20V, V_{GS} = 10V, I_D = 85A,$	-	125	-	nC
Gate-Source Charge	$Q_{gs}$		-	18	-	
Gate-Drain Charge	$Q_{gd}$		-	14	-	
Input Capacitance	$C_{iss}$	$V_{DS} = 20V, V_{GS} = 0V, f = 1\text{MHz}$	-	7500	-	pF
Output Capacitance	$C_{oss}$		-	1950	-	
Reverse Transfer Capacitance	$C_{rss}$		-	120	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 20V, R_g = 1.6\Omega, V_{GS} = 10V, I_D = 85A, R_L = 0.5\Omega$	-	15	-	ns
Turn-On Rise Time	$t_r$		-	9	-	
Turn-Off Delay Time	$t_{d(off)}$		-	60	-	
Turn-Off Fall Time	$t_f$		-	11	-	
<b>Source-Drain Diode Characteristics</b>						
Diode Forward Current	$I_{SD}$		-	-	250	A
Diode Forward Voltage	$V_{SD}$	$I_S = 80A, V_{GS} = 0V$	-	-	1.2	V
Reverse Recovery Time	$t_{rr}$	$I_S = 170A, T_J = 25^\circ\text{C}, di_f/dt = 100A/\mu s, V_{GS} = 0V$	-	35	-	ns
Reverse Recovery Charge	$Q_{rr}$		-	125	-	$\mu C$

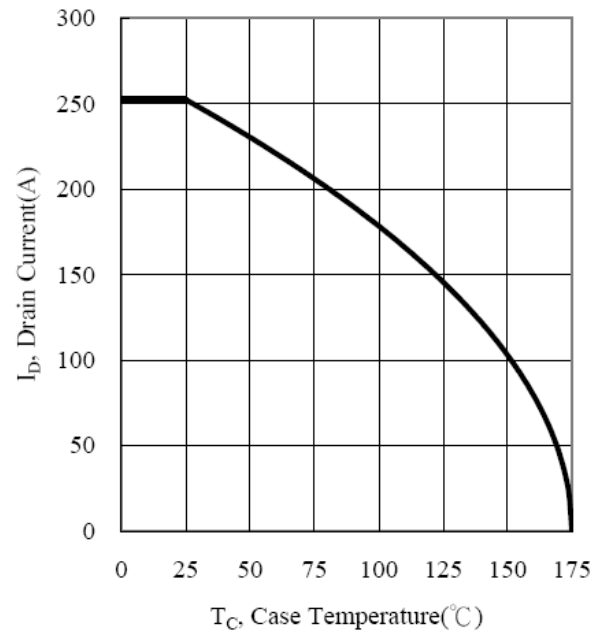


### Electrical Characteristics Curves

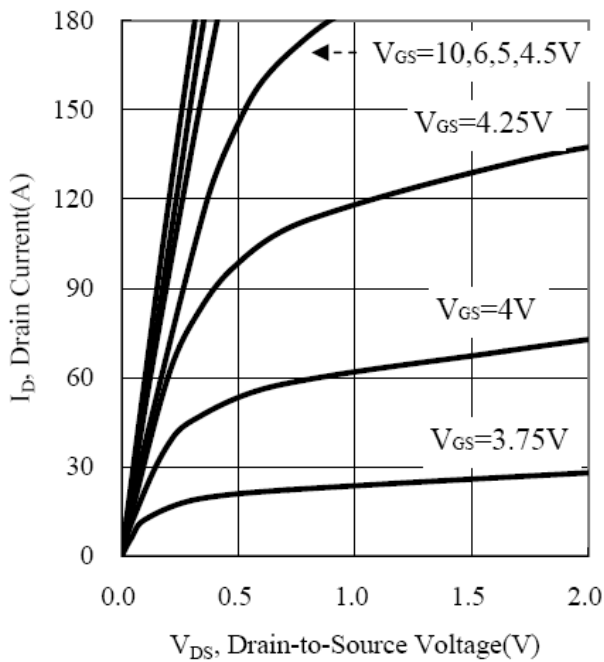
1. Power Dissipation



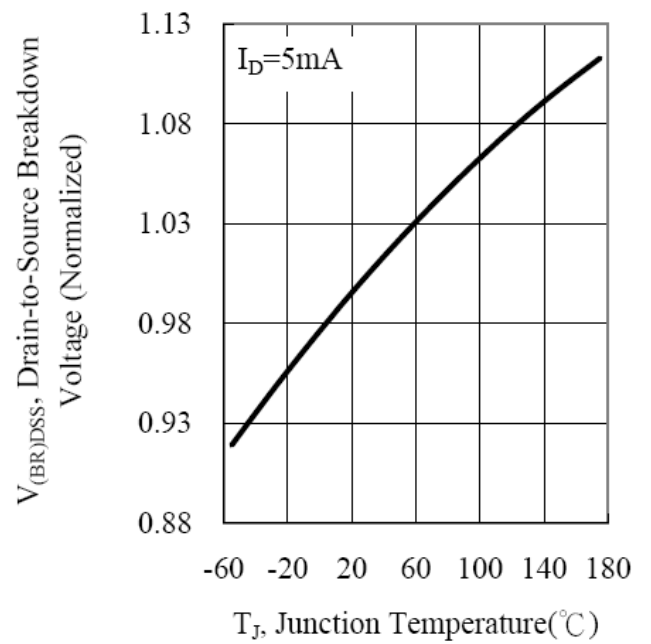
2. Drain Current



3. Output Characteristics  $T_C=25^\circ\text{C}$

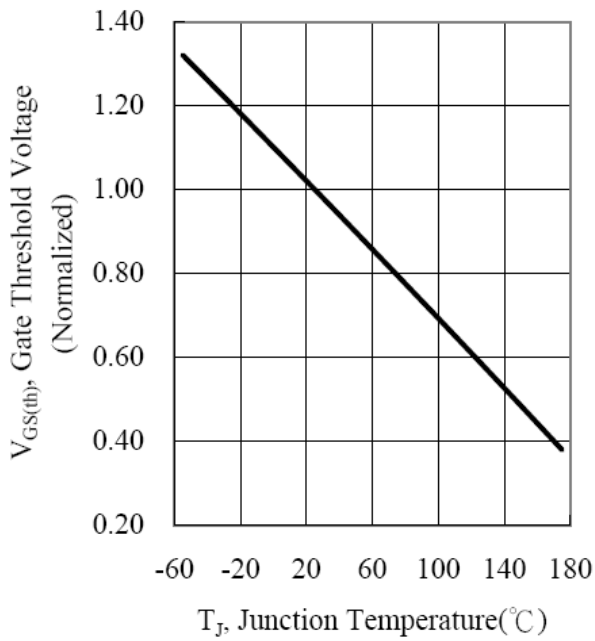


4. Drain-to-Source Breakdown Voltage

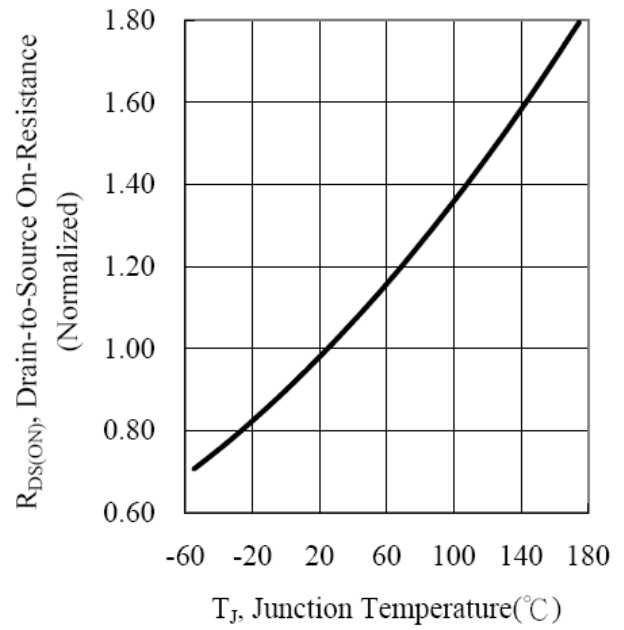




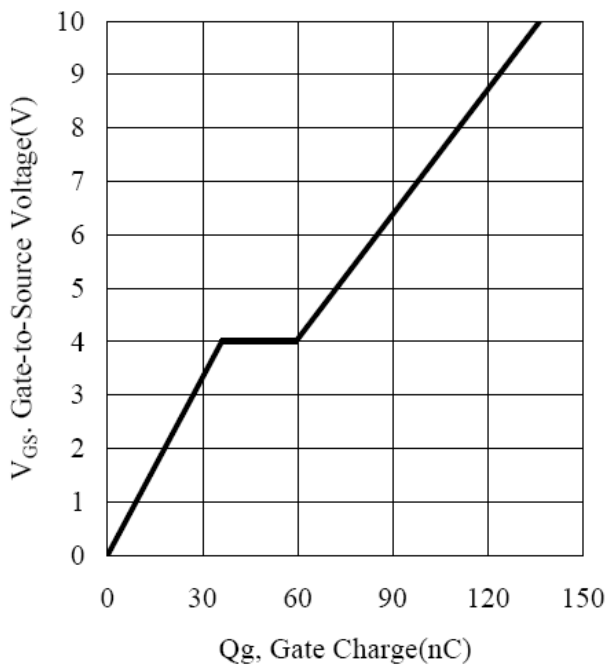
5. Gate Threshold Voltage



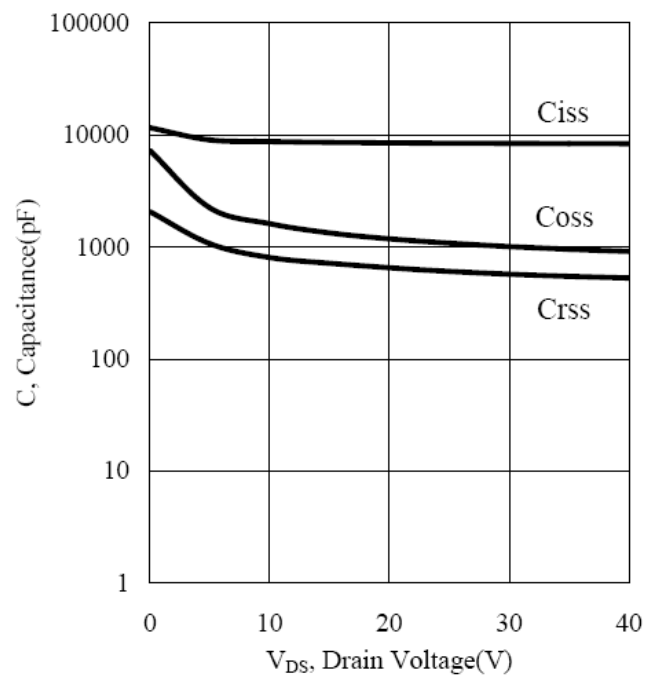
6. Drain-to-Source On-Resistance



7. Typ. Gate Charge

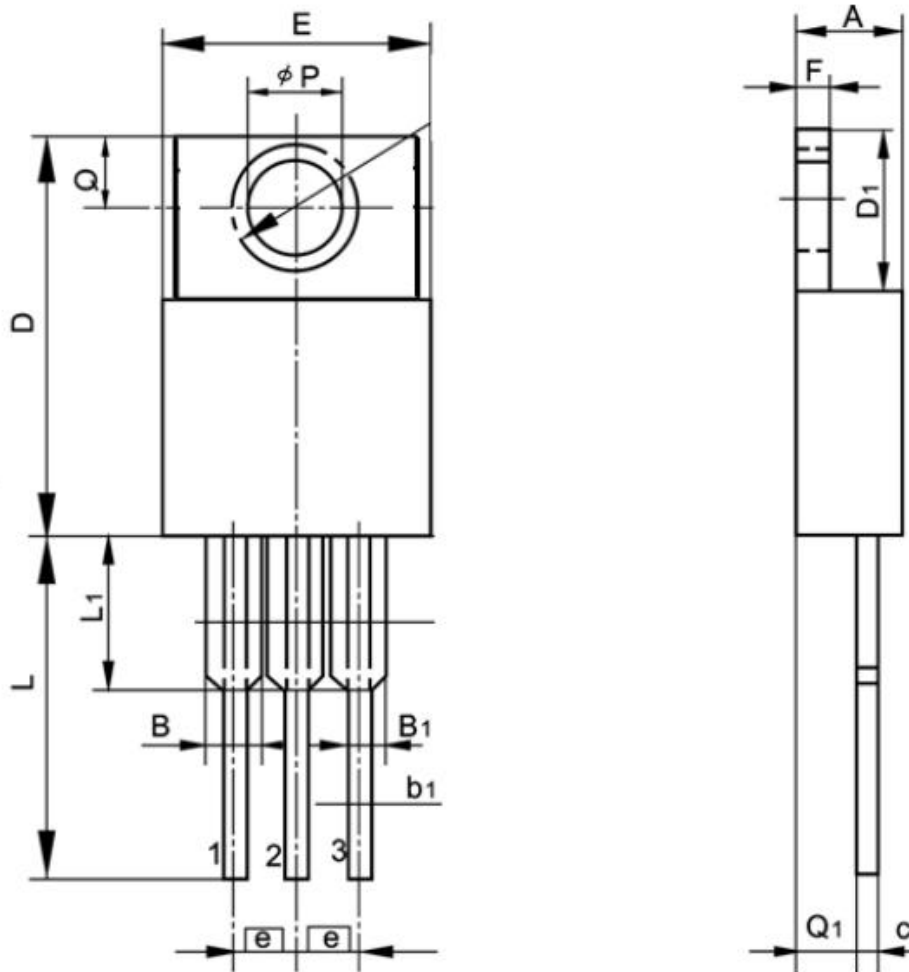


8. Typ. Capacitance





**Package Outline**



**TO-220 MECHANICAL DATA**

UNIT: mm

SYMBOL	min	nom	max	SYMBOL	min	nom	max
A	4.00		4.80	E	9.70		10.70
B	1.15		1.45	e		2.54	
B1	0.90		1.40	F	1.10		1.40
b1	0.65		0.95	L	12.50		14.50
c	0.30		0.50	L1	2.90	3.40	3.90
D	14.40		16.40	Q	2.50		3.10
D1	5.90		6.90	Q1	2.00		3.00
				φ P	3.60		4.00